Panasonic INDUSTRY

Flexural modulus
25℃ 35GPa

CTE x, y-axis
9ppm/℃

Tg(DMA) 250℃

Applications
IC Package
IC substrate

LEXCM GX

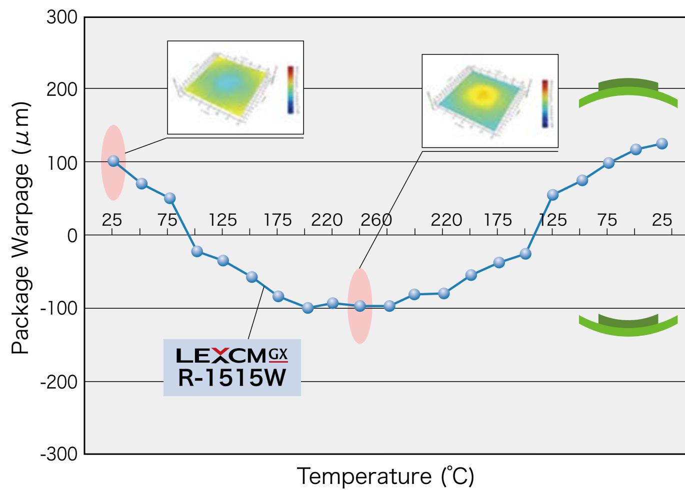
Laminate
R-1515W

Prepreg
R-1410W

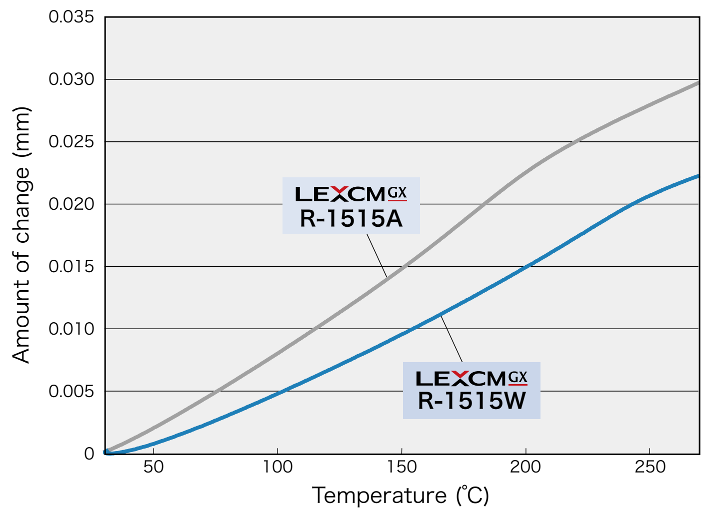
High elasticity Low CTE IC substrate materials

Achieve more functionality (multi-pin and integrated circuit) the large-sized Package by excellent modulus and highly heat resistant property.

IC package warpage

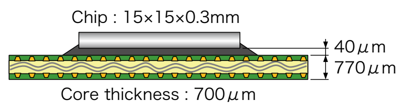


Thermal expansion (x-axis)



Length : 10mm
Thickness : 0.8mm (8ply)
Method : TMA

Construction



General properties

Item		Test method	Condition	Unit	LEXCM GX R-1515W
Glass transition temp.(Tg)		DMA*2	A	℃	**250**
Thermal decomposition temp.(Td)		TGA	A	℃	**390**
CTE x-axis	α1	Internal method	A	ppm/℃	**9**
CTE y-axis					**9**
CTE z-axis	α1	IPC-TM-650 2.4.24	A		**22**
	α2				**97**
Flexural modulus*1		JIS C 6481	25℃	GPa	**35**
			250℃		**21**

The sample thickness is 0.1 mm.
*1 0.8mm *2 Measurement in bending mode
Please see our website for Notes before you use.

Our Halogen-free materials are based on JPCA-ES-01-2003 standard and others.
The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials
Panasonic Industry R-1515W

Panasonic Industry Co., Ltd. Electronic Materials Business Division

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